3.3 V/2.5 V LVCMOS 1:12 Clock Fanout Buffer

MPC9448

PRODUCT DISCONTINUATION NOTICE - LAST TIME BUY EXPIRES SEPTEMBER 7, 2016

DATASHEET

The Freescale Semiconductor, Inc. MPC9448 is a 3.3 V or 2.5 V compatible, 1:12 clock fanout buffer targeted for high performance clock tree applications. With output frequencies up to 350 MHz and output skews less than 150 ps, the device meets the needs of most demanding clock applications.

LOW VOLTAGE
3.3 V/2.5 V LVCMOS 1:12
CLOCK FANOUT BUFFER

AC SUFFIX
32-LEAD LQFP PACKAGE
Pb-FREE PACKAGE
CASE 873A-03

Features

- 12 LVCMOS compatible clock outputs
- Selectable LVCMOS and differential LVPECL compatible clock inputs
- Maximum clock frequency of 350 MHz
- Maximum clock skew of 150 ps
- Synchronous output stop in logic low state eliminates output runt pulses
- High-impedance output control
- 3.3 V or 2.5 V power supply
- Drives up to 24 series terminated clock lines
- Ambient temperature range -40°C to +85°C
- 32-Lead LQFP packaging, Pb-free
- Supports clock distribution in networking, telecommunication and computing applications
- Pin and function compatible to MPC948
- For drop in replacement part use 83948AYI-147

Functional Description

The MPC9448 is specifically designed to distribute LVCMOS compatible clock signals up to a frequency of 350 MHz. Each output provides a precise copy of the input signal with a near zero skew. The outputs buffers support driving of 50 Ω terminated transmission lines on the incident edge. Each output is capable of driving either one parallel terminated or two series terminated transmission lines.

Two selectable, independent clock inputs are available, providing support of LVCMOS and differential LVPECL clock distribution systems. The MPC9448 $\overline{\text{CLK\_STOP}}$ control is synchronous to the falling edge of the input clock. It allows the start and stop of the output clock signal only in a logic low state, thus eliminating potential output runt pulses. Applying the OE control will force the outputs into high-impedance mode.

All inputs have an internal pull-up or pull-down resistor preventing unused and open inputs from floating. The device supports a 2.5 V or 3.3 V power supply and an ambient temperature range of -40°C to +85°C. The MPC9448 is pin and function compatible but performance-enhanced to the MPC948.

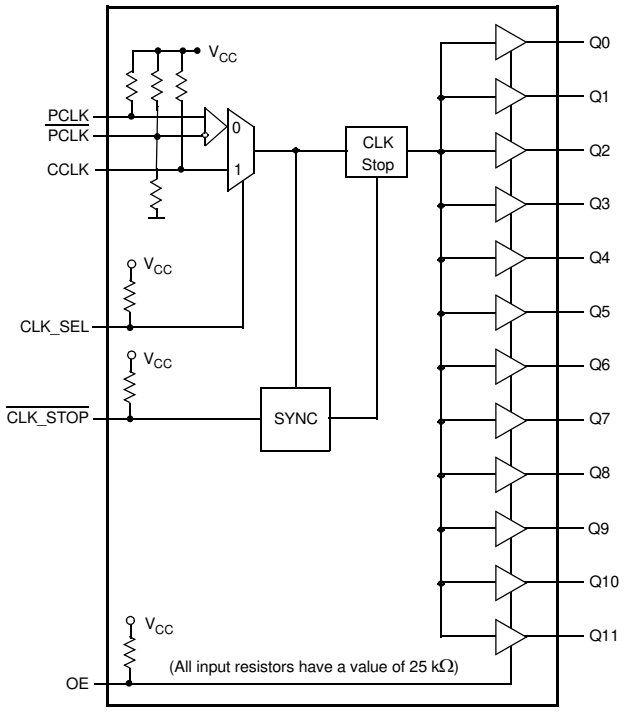


Figure 1. Logic Diagram

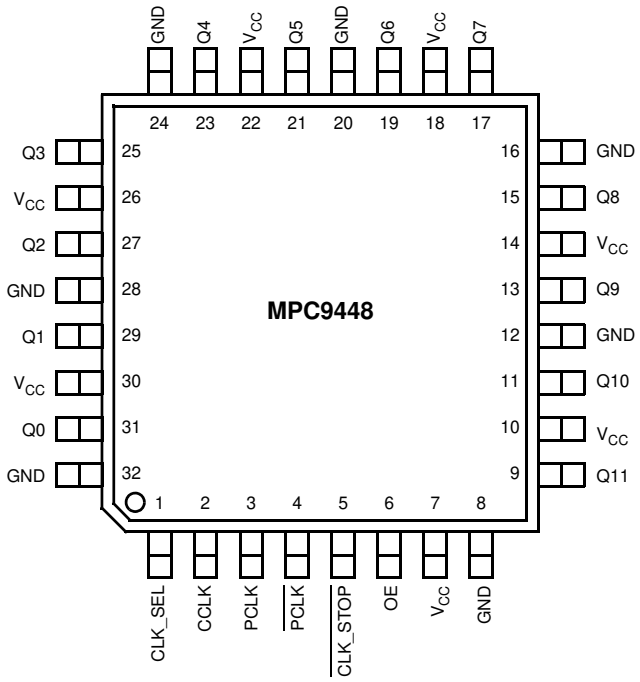


Figure 2. 32-Lead Pinout (Top View)

Table 1. Function Table

Control	Default	0	1
CLK_SEL	1	PECL differential input selected	CCLK input selected
OE	1	Outputs disabled (high-impedance state)(1)	Outputs enabled
$\overline{\text{CLK\_STOP}}$	1	Outputs synchronously stopped in logic low state	Outputs active

1. OE = 0 will high-impedance tristate all outputs independent on $\overline{\text{CLK\_STOP}}$.

Table 2. Pin Configurations

Pin	I/O	Type	Function
PCLK, $\overline{\text{PCLK}}$	Input	LVPECL	Clock signal input
CCLK	Input	LVCMOS	Alternative clock signal input
CLK_SEL	Input	LVCMOS	Clock input select
$\overline{\text{CLK\_STOP}}$	Input	LVCMOS	Clock output enable/disable
OE	Input	LVCMOS	Output enable/disable (high-impedance tristate)
Q0–11	Output	LVCMOS	Clock outputs
GND	Supply	Ground	Negative power supply (GND)
V_{CC}	Supply	V_{CC}	Positive power supply for I/O and core. All V_{CC} pins must be connected to the positive power supply for correct operation

Table 3. Absolute Maximum Ratings(1)

Symbol	Characteristics	Min	Max	Unit
V_{CC}	Supply Voltage	–0.3	3.9	V
V_{IN}	DC Input Voltage	–0.3	V_{CC} + 0.3	V
V_{OUT}	DC Output Voltage	–0.3	V_{CC} + 0.3	V
I_{IN}	DC Input Current		±20	mA
I_{OUT}	DC Output Current		±50	mA
T_{Stor}	Storage temperature	–65	125	°C

1. Absolute maximum continuous ratings are those maximum values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation at absolute-maximum-rated conditions is not implied.

Table 4. General Specifications

Symbol	Characteristics	Min	Typ	Max	Unit	Condition
V_{TT}	Output Termination Voltage		$V_{CC} \div 2$		V	
MM	ESD Protection (Machine model)	200			V	
HBM	ESD Protection (Human body model)	2000			V	
LU	Latch-up Immunity	200			mA	
C_{PD}	Power Dissipation Capacitance		10		pF	Per output
C_{IN}	Input Capacitance		4.0		pF	Inputs

Table 5. DC Characteristics (V_{CC} = 3.3 V ± 5%, T_A = -40°C to +85°C)

Symbol	Characteristics		Min	Typ	Max	Unit	Condition
V_{IH}	Input HIGH Voltage		2.0		V_{CC} + 0.3	V	LVCMOS
V_{IL}	Input LOW Voltage		–0.3		0.8	V	LVCMOS
V_{PP}	Peak-to-Peak Input Voltage	PCLK	250			mV	LVPECL
V_{CMR}(1)	Common Mode Range	PCLK	1.1		V_{CC} – 0.6	V	LVPECL
I_{IN}	Input Current(2)				300	µA	V_{IN} = V_{CC} or GND
V_{OH}	Output HIGH Voltage		2.4			V	I_{OH} = –24 mA(3)
V_{OL}	Output LOW Voltage				0.55 0.30	V V	I_{OL} = 24 mA(3) I_{OL} = 12 mA
Z_{OUT}	Output Impedance			17		Ω	
I_{CCQ}(4)	Maximum Quiescent Supply Current				2.0	mA	All V_{CC} Pins

1. V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (DC) specification.
2. Input pull-up / pull-down resistors influence input current.
3. The MPC9448 is capable of driving 50 Ω transmission lines on the incident edge. Each output drives one 50 Ω parallel terminated transmission line to a termination voltage of V_{TT}. Alternatively, the device drives up to two 50 Ω series terminated transmission lines (for V_{CC} = 3.3 V) or one 50 Ω series terminated transmission line (for V_{CC} = 2.5 V).
4. I_{CCQ} is the DC current consumption of the device with all outputs open and the input in its default state or open.

Table 6. AC Characteristics (V_{CC} = 3.3 V ± 5%, T_A = -40°C to +85°C)[1]

Symbol	Characteristics		Min	Typ	Max	Unit	Condition
f_{ref}	Input Frequency		0		350	MHz	
f_{MAX}	Maximum Output Frequency		0		350	MHz	
V_{PP}	Peak-to-Peak Input Voltage	PCLK	400		1000	mV	LVPECL
V_{CMR}[2]	Common Mode Range	PCLK	1.3		V_{CC} – 0.8	V	LVPECL
$t_{P, REF}$	Reference Input Pulse Width		1.4			ns	
t_r, t_f	CCLK Input Rise/Fall Time				1.0[3]	ns	0.8 to 2.0 V
$t_{PLH/HL}$ $t_{PLH/HL}$	Propagation Delay	PCLK to any Q CCLK to any Q	1.6 1.3		3.6 3.3	ns ns	
$t_{PLZ, HZ}$	Output Disable Time				11	ns	
$t_{PZL, LZ}$	Output Enable Time				11	ns	
t_S	Setup Time	CCLK to $\overline{CLK\_STOP}$ PCLK to $\overline{CLK\_STOP}$	0.0 0.0			ns ns	
t_H	Hold Time	CCLK to $\overline{CLK\_STOP}$ PCLK to $\overline{CLK\_STOP}$	1.0 1.5			ns ns	
$t_{sk(O)}$	Output-to-Output Skew				150	ps	
$t_{sk(PP)}$	Device-to-Device Skew	PCLK or CCLK to any Q			2.0	ns	
$t_{SK(P)}$	Output Pulse skew[4]	Using CCLK Using PCLK			300 400	ps ps	
DC_Q	Output Duty Cycle	f_Q<170 MHz	45	50	55	%	DC_{REF} = 50%
t_r, t_f	Output Rise/Fall Time		0.1		1.0	ns	0.55 to 2.4 V

1. AC characteristics apply for parallel output termination of 50 Ω to V_{TT}.
2. V_{CMR} (AC) is the crosspoint of the differential input signal. Normal AC operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (AC) specification. Violation of V_{CMR} or V_{PP} impacts $t_{PLH/HL}$ and $t_{SK(PP)}$.
3. Violation of the 1.0 ns maximum input rise and fall time limit will affect the device propagation delay, device-to-device skew, reference input pulse width, output duty cycle and maximum frequency specifications.
4. Output pulse skew is the absolute difference of the propagation delay times: | t_{pLH} – t_{pHL} |.

Table 7. DC Characteristics (V_{CC} = 2.5 V ± 5%, T_A = -40°C to +85°C)

Symbol	Characteristics		Min	Typ	Max	Unit	Condition
V_{IH}	Input high voltage		1.7		V_{CC} + 0.3	V	LVCMOS
V_{IL}	Input low voltage		–0.3		0.7	V	LVCMOS
V_{PP}	Peak-to-peak input voltage	PCLK	250			mV	LVPECL
V_{CMR}[1]	Common Mode Range	PCLK	1.0		V_{CC} – 0.7	V	LVPECL
I_{IN}	Input current[2]				300	µA	V_{IN} = GND or V_{IN} = V_{CC}
V_{OH}	Output High Voltage		1.8			V	I_{OH} = –15 mA[3]
V_{OL}	Output Low Voltage				0.6	V	I_{OL}= 15 mA[3]
Z_{OUT}	Output impedance			19		Ω	
I_{CCQ}[4]	Maximum Quiescent Supply Current				2.0	mA	All V_{CC} Pins

1. V_{CMR} (DC) is the crosspoint of the differential input signal. Functional operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (DC) specification.
2. Input pull-up / pull-down resistors influence input current.
3. The MPC9448 is capable of driving 50 Ω transmission lines on the incident edge. Each output drives one 50 Ω parallel terminated transmission line to a termination voltage of V_{TT}. Alternatively, the device drives one 50 Ω series terminated transmission lines at V_{CC} = 2.5 V.
4. I_{CCQ} is the DC current consumption of the device with all outputs open and the input in its default state or open.

Table 8. AC Characteristics (V_{CC} = 2.5 V ± 5%, T_A = -40°C to +85°C)[1]

Symbol	Characteristics		Min	Typ	Max	Unit	Condition
f_{ref}	Input Frequency		0		350	MHz	
f_{MAX}	Maximum Output Frequency		0		350	MHz	
V_{PP}	Peak-to-peak input voltage	PCLK	400		1000	mV	LVPECL
V_{CMR}[2]	Common Mode Range	PCLK	1.2		V_{CC} – 0.8	V	LVPECL
$t_{P, REF}$	Reference Input Pulse Width		1.4			ns	
t_r, t_f	CCLK Input Rise/Fall Time				1.0[3]	ns	0.8 to 2.0 V
$t_{PLH/HL}$ $t_{PLH/HL}$	Propagation delay	PCLK to any Q CCLK to any Q	1.5 1.7		4.2 4.4	ns ns	
$t_{PLZ, HZ}$	Output Disable Time				11	ns	
$t_{PZL, LZ}$	Output Enable Time				11	ns	
t_S	Setup time	CCLK to $\overline{CLK\_STOP}$ PCLK to $\overline{CLK\_STOP}$	0.0 0.0			ns ns	
t_H	Hold time	CCLK to $\overline{CLK\_STOP}$ PCLK to $\overline{CLK\_STOP}$	1.0 1.5			ns ns	
$t_{sk(O)}$	Output-to-output Skew				150	ps	
$t_{sk(PP)}$	Device-to-device Skew	PCLK or CCLK to any Q			2.7	ns	
$t_{SK(p)}$	Output pulse skew[4]	Using CCLK Using PCLK			200 300	ps ps	
DC_Q	Output Duty Cycle	f_Q< 350 MHz and using CCLK f_Q<200 MHz and using PCLK	45 45	50 50	55 55	% %	DC_{REF} = 50%
t_r, t_f	Output Rise/Fall Time		0.1		1.0	ns	0.6 to 1.8 V

1. AC characteristics apply for parallel output termination of 50 Ω to V_{TT}.
2. V_{CMR} (AC) is the crosspoint of the differential input signal. Normal AC operation is obtained when the crosspoint is within the V_{CMR} range and the input swing lies within the V_{PP} (AC) specification. Violation of V_{CMR} or V_{PP} impacts $t_{PLH/HL}$ and $t_{SK(PP)}$.
3. Violation of the 1.0 ns maximum input rise and fall time limit will affect the device propagation delay, device-to-device skew, reference input pulse width, output duty cycle and maximum frequency specifications.
4. Output pulse skew is the absolute difference of the propagation delay times: $| t_{pLH} - t_{pHL} |$.

APPLICATION INFORMATION

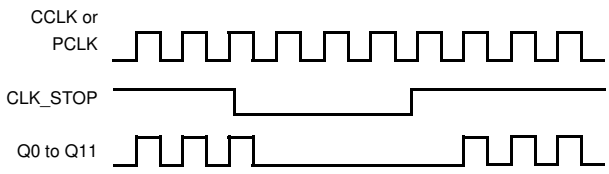


Figure 3. Output Clock Stop (CLK_STOP) Timing Diagram

Driving Transmission Lines

The MPC9448 clock driver was designed to drive high-speed signals in a terminated transmission line environment. To provide the optimum flexibility to the user, the output drivers were designed to exhibit the lowest impedance possible. With an output impedance of 17 Ω (V_{CC} = 3.3 V), the outputs can drive either parallel or series terminated transmission lines. For more information on transmission lines, the reader is referred to Freescale application note AN1091. In most high performance clock networks, point-to-point distribution of signals is the method of choice. In a point-to-point scheme, either series terminated or parallel terminated transmission lines can be used. The parallel technique terminates the signal at the end of the line with a 50 Ω resistance to V_{CC}÷2.

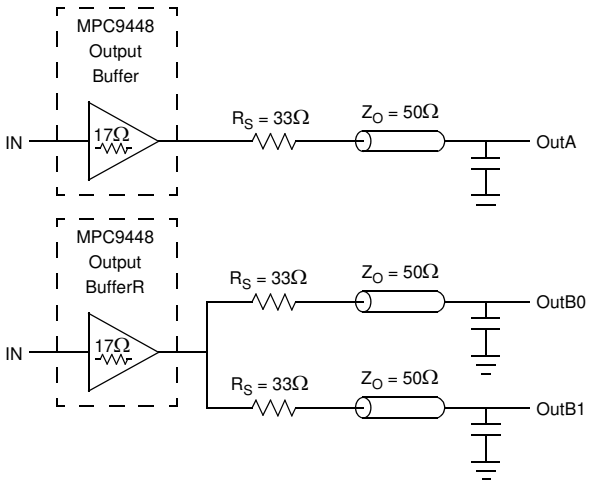


Figure 4. Single versus Dual Transmission Lines

This technique draws a fairly high level of DC current ,and thus, only a single terminated line can be driven by each output of the MPC9448 clock driver. For the series terminated case, however, there is no DC current draw; thus, the outputs can drive multiple series terminated lines. Figure 4 illustrates an output driving a single series terminated line versus two series terminated lines in parallel. When taken to its extreme, the fanout of the MPC9448 clock driver is effectively doubled due to its capability to drive multiple lines at V_{CC} = 3.3 V.

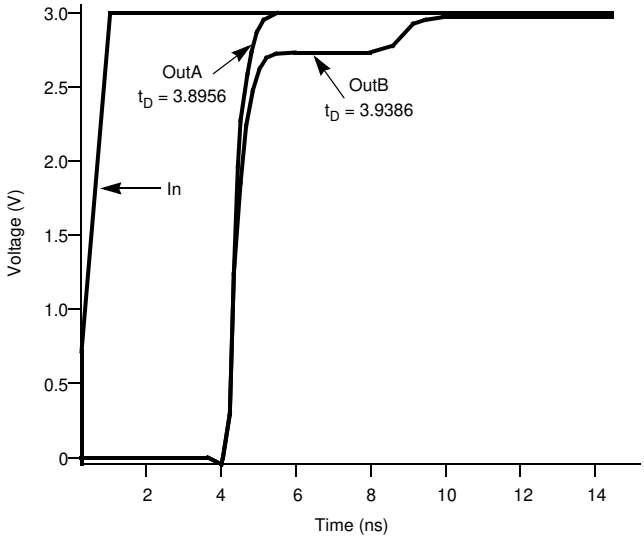


Figure 5. Single versus Dual Line Termination Waveforms

The waveform plots in Figure 5 show the simulation results of an output driving a single line versus two lines. In both cases, the drive capability of the MPC9448 output buffer is more than sufficient to drive 50 Ω transmission lines on the incident edge. Note from the delay measurements in the simulations, a delta of only 43 ps exists between the two differently loaded outputs. This suggests that the dual line driving need not be used exclusively to maintain the tight output-to-output skew of the MPC9448. The output waveform in Figure 5 shows a step in the waveform. This step is caused by the impedance mismatch seen looking into the driver. The parallel combination of the 33 Ω series resistor plus the output impedance does not match the parallel combination of the line impedances. The voltage wave launched down the two lines will equal:

$$V_L = V_S (Z_0 \div (R_S + R_0 + Z_0))$$
$$Z_0 = 50\ \Omega \parallel 50\ \Omega$$
$$R_S = 33\ \Omega \parallel 33\ \Omega$$
$$R_0 = 17\ \Omega$$
$$V_L = 3.0\ (25 \div (16.5+17+25)$$
$$= 1.28\ V$$

At the load end, the voltage will double, due to the near unity reflection coefficient, to 2.5 V. It will then increment towards the quiescent 3.0 V in steps separated by one round trip delay (in this case 4.0 ns).

Since this step is well above the threshold region, it will not cause any false clock triggering; however, designers may be uncomfortable with unwanted reflections on the line. To better match the impedances when driving multiple lines, the situation in Figure 6 should be used. In this case, the series terminating resistors are reduced such that when the parallel combination is added to the output buffer impedance, the line impedance is perfectly matched.

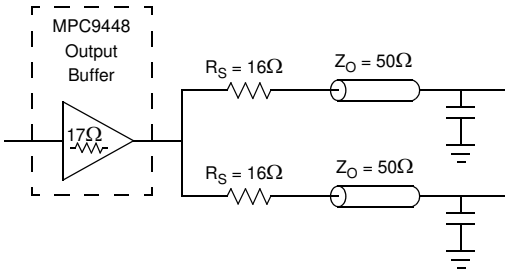


Figure 6. Optimized Dual Line Termination

Power Consumption of the MPC9448 and Thermal Management

The MPC9448 AC specification is guaranteed for the entire operating frequency range up to 350 MHz. The MPC9448 power consumption, and the associated long-term reliability, may decrease the maximum frequency limit, depending on operating conditions such as clock frequency, supply voltage, output loading, ambient temperature, vertical convection and thermal conductivity of package and board. This section describes the impact of these parameters on the junction temperature and gives a guideline to estimate the MPC9448 die junction temperature and the associated device reliability. For a complete analysis of power consumption as a function of operating conditions and associated long term device reliability, please refer to the Freescale application note AN1545. According the AN1545, the long-term device reliability is a function of the die junction temperature:

Table 9. Die Junction Temperature and MTFB

Junction Temperature (°C)	MTBF (Years)
100	20.4
110	9.1
120	4.2
130	2.0

Increased power consumption will increase the die junction temperature and impact the device reliability (MTBF). According to the system-defined tolerable MTBF, the die junction temperature of the MPC9448 needs to be controlled, and the thermal impedance of the board/package should be optimized. The power dissipated in the MPC9448 is represented in equation 1.

Where I_{CCQ} is the static current consumption of the MPC9448, C_{PD} is the power dissipation capacitance per output. $(M)\Sigma C_L$ represents the external capacitive output load, and N is the number of active outputs (N is always 12 in case of the MPC9448). The MPC9448 supports driving transmission lines to maintain high signal integrity and tight timing parameters. Any transmission line will hide the lumped capacitive load at the end of the board trace, therefore, ΣC_L is zero for controlled transmission line systems and can be eliminated from equation 1. Using parallel termination output, termination results in equation 2 for power dissipation.

In equation 2, P stands for the number of outputs with a parallel or thevenin termination. V_{OL}, I_{OL}, V_{OH} and I_{OH} are a function of the output termination technique, and DC_Q is the clock signal duty cycle. If transmission lines are used, ΣC_L is zero in equation 2 and can be eliminated. In general, the use of controlled transmission line techniques eliminates the impact of the lumped capacitive loads at the end lines and greatly reduces the power dissipation of the device. Equation 3 describes the die junction temperature T_J as a function of the power consumption.

Where R_{thja} is the thermal impedance of the package (junction to ambient), and T_A is the ambient temperature. According to Figure 9, the junction temperature can be used to estimate the long-term device reliability. Further, combining equation 1 and equation 2 results in a maximum operating frequency for the MPC9448 in a series terminated transmission line system, equation 4.

$$P_{TOT} = \left[I_{CCQ} + V_{CC} \cdot f_{CLOCK} \cdot \left(N \cdot C_{PD} + \sum_{M} C_L \right) \right] \cdot V_{CC} \quad \text{Equation 1}$$

$$P_{TOT} = V_{CC} \cdot \left[I_{CCQ} + V_{CC} \cdot f_{CLOCK} \cdot \left(N \cdot C_{PD} + \sum_{M} C_L \right) \right] + \sum_{P} \left[DC_Q \cdot I_{OH} \cdot (V_{CC} - V_{OH}) + (1 - DC_Q) \cdot I_{OL} \cdot V_{OL} \right] \quad \text{Equation 2}$$

$$T_J = T_A + P_{TOT} \cdot R_{thja} \quad \text{Equation 3}$$

$$f_{CLOCK,MAX} = \frac{1}{C_{PD} \cdot N \cdot V_{CC}^2} \cdot \left[\frac{T_{j,MAX} - T_A}{R_{thja}} - (I_{CCQ} \cdot V_{CC}) \right] \quad \text{Equation 4}$$

$T_{J,MAX}$ should be selected according to the MTBF system requirements, and Figure 9 R_{thja} can be derived from Figure 10. The R_{thja} represent data based on 1S2P boards. Using 2S2P boards will result in a lower thermal impedance than indicated below.

Table 10. Thermal Package Impedance of the 32ld LQFP

Convection, LFPM	R_{thja} (1P2S board), °C/W	R_{thja} (2P2S board), °C/W
Still air	86	61
100 lfpm	76	56
200 lfpm	71	54
300 lfpm	68	53
400 lfpm	66	52
500 lfpm	60	49

If the calculated maximum frequency is below 350 MHz, it becomes the upper clock speed limit for the given application conditions. The following eight derating charts describe the safe frequency operation range for the MPC9448. The charts were calculated for a maximum tolerable die junction temperature of 110°C (120°C), corresponding to an estimated MTBF of 9.1 years (4 years), a supply voltage of 3.3 V and series terminated transmission line or capacitive loading. Depending on a given set of these operating conditions and the available device convection, a decision on the maximum operating frequency can be made.

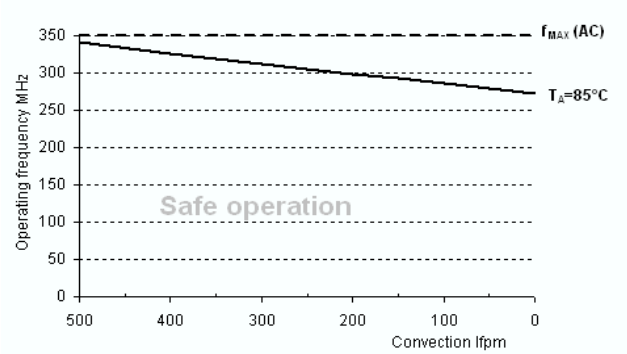


Figure 7. Maximum MPC9448 Frequency, V_{CC} = 3.3 V, MTBF 9.1 Years, Driving Series Terminated transmission lines, 2s2p board

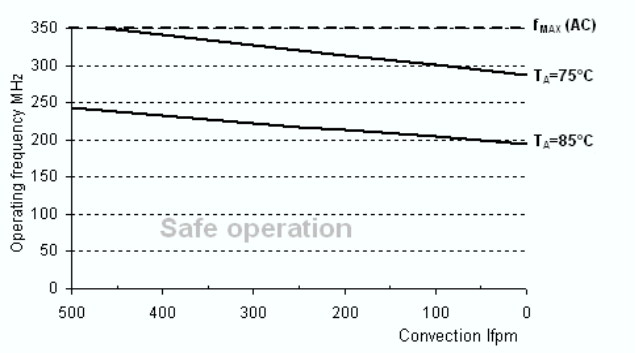


Figure 8. Maximum MPC9448 frequency, V_{CC} = 3.3 V, MTBF 9.1 Years, 4 pF Load per Line, 2s2p Board

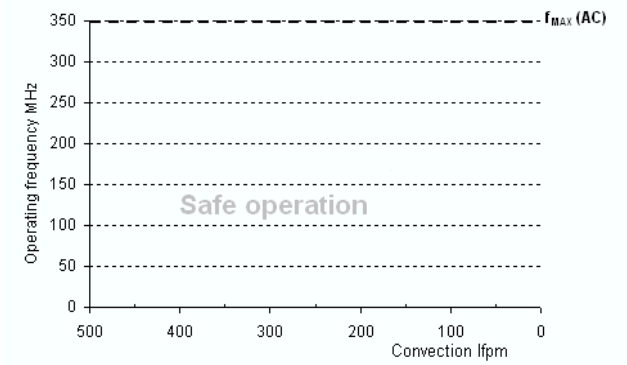


Figure 9. No maximum Frequency Limitation for V_{CC} = 3.3 V, MTBF 4 Years, Driving Series Terminated Transmission Lines, 2s2p Board

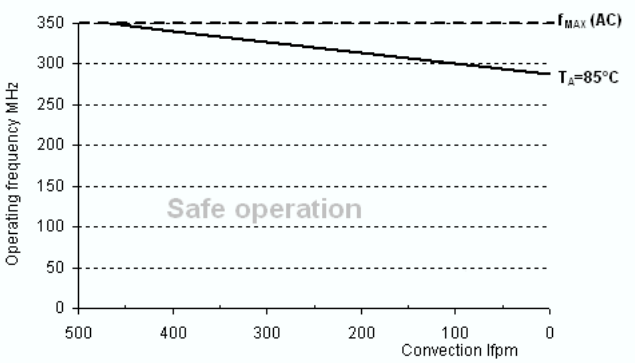


Figure 10. Maximum MPC9448 Frequency, V_{CC} = 3.3 V, MTBF 4 Years, 4 pF Load per Line, 2s2p Board

The Following Figures Illustrate the Measurement Reference for the MPC9448 Clock Driver Circuit

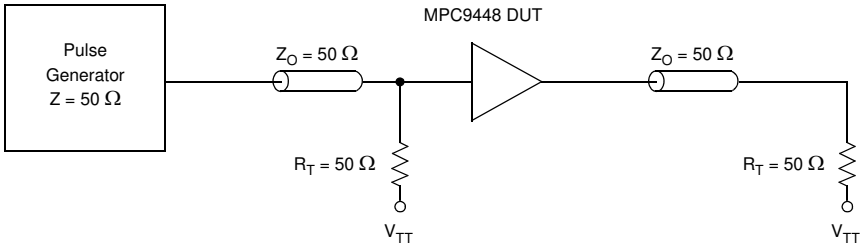


Figure 11. CCLK MPC9448 AC Test Reference for V_{CC} = 3.3 V and V_{CC} = 2.5 V

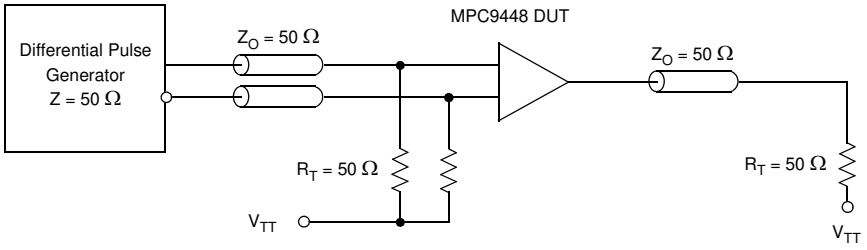


Figure 12. PCLK MPC9448 AC Test Reference

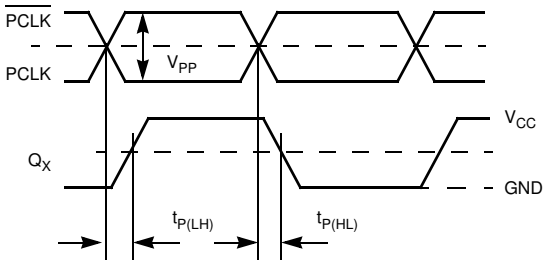


Figure 13. Propagation Delay (t_{PD}) Test Reference

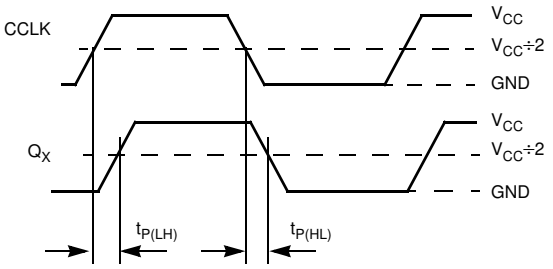
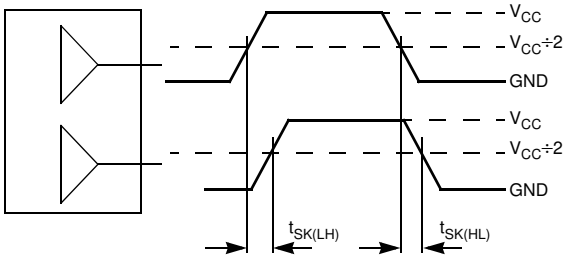


Figure 14. Propagation Delay (t_{PD}) Test Reference



The pin-to-pin skew is defined as the worst case difference in propagation delay between any similar delay path within a single device.

Figure 15. Output-to-Output Skew $t_{SK(LH, HL)}$

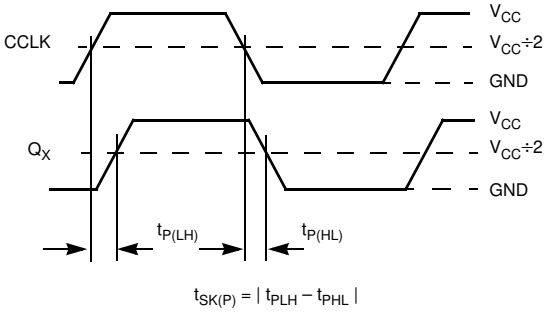
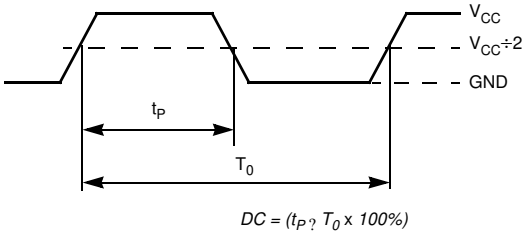


Figure 16. Output Pulse Skew ($t_{SK(P)}$) Test Reference



The time from the output controlled edge to the non-controlled edge, divided by the time between output controlled edges, expressed as a percentage.

Figure 17. Output Duty Cycle (DC)

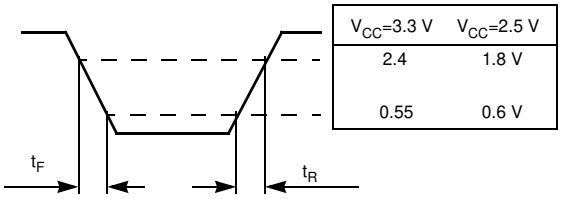
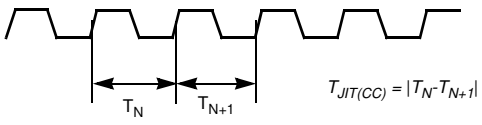


Figure 18. Output Transition Time Test Reference



The variation in cycle time of a signal between adjacent cycles, over a random sample of adjacent cycle pairs.

Figure 19. Cycle-to-Cycle Jitter

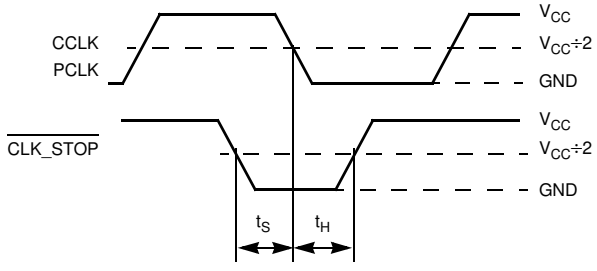
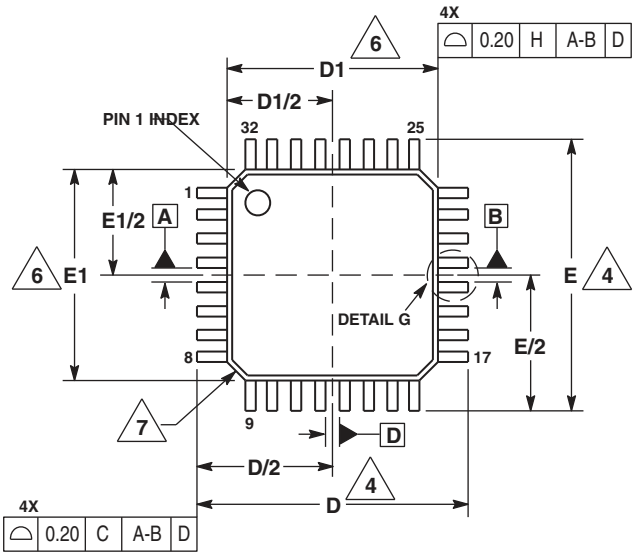
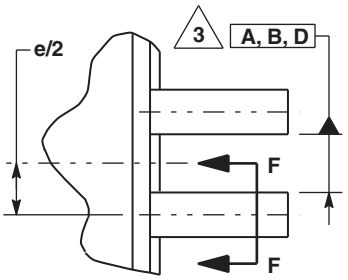


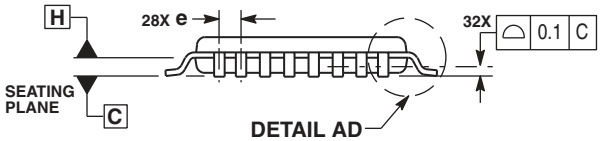
Figure 20. Setup and Hold Time (t_S, t_H) Test Reference

PACKAGE DIMENSIONS

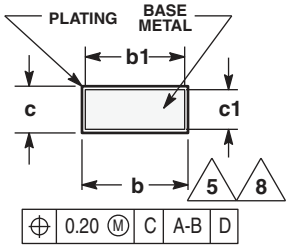




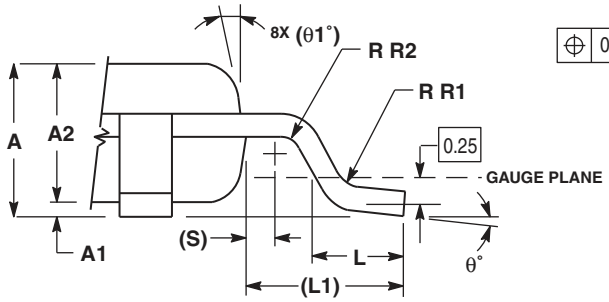
DETAIL G



DETAIL AD



SECTION F-F



DETAIL AD

NOTES:
1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DATUMS A, B, AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS D AND E TO BE DETERMINED AT SEATING PLANE C.
5. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE MAXIMUM b DIMENSION BY MORE THAN 0.08-mm. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD OR PROTRUSION: 0.07-mm.
6. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25-mm PER SIDE. D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE DIMENSIONS INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1-mm AND 0.25-mm FROM THE LEAD TIP.

	MILLIMETERS	
DIM	MIN	MAX
A	1.40	1.60
A1	0.05	0.15
A2	1.35	1.45
b	0.30	0.45
b1	0.30	0.40
c	0.09	0.20
c1	0.09	0.16
D	9.00 BSC	
D1	7.00 BSC	
e	0.80 BSC	
E	9.00 BSC	
E1	7.00 BSC	
L	0.50	0.70
L1	1.00 REF	
q	0°	7°
q1	12 REF	
R1	0.08	0.20
R2	0.08	---
S	0.20 REF	

CASE 873A-03
ISSUE B
32-LEAD LQFP PACKAGE

Revision History Sheet

Rev	Table	Page	Description of Change	Date
7		1	NRND – Not Recommend for New Designs	12/21/12
7		1	Removed NRND - Not Recommended for New Designs	2/13/15
7		1	Product Discontinuation Notice - Last time buy expires September 7, 2016. PDN N-16-02	3/15/16

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